

**NP40N10YDF, NP40N10VDF, NP40N10PDF**

R07DS0361EJ0100

Rev.1.00

**MOS FIELD EFFECT TRANSISTOR**

Jun 07, 2011

**Description**

These products are N-channel MOS Field Effect Transistors designed for high current switching applications.

**Features**

- Low on-state resistance
  - $R_{DS(on)} = 25 \text{ m}\Omega \text{ MAX.}$  ( $V_{GS} = 10 \text{ V}$ ,  $I_D = 20 \text{ A}$ ) (NP40N10YDF)
  - $R_{DS(on)} = 26 \text{ m}\Omega \text{ MAX.}$  ( $V_{GS} = 10 \text{ V}$ ,  $I_D = 20 \text{ A}$ ) (NP40N10VDF)
  - $R_{DS(on)} = 27 \text{ m}\Omega \text{ MAX.}$  ( $V_{GS} = 10 \text{ V}$ ,  $I_D = 20 \text{ A}$ ) (NP40N10PDF)
- Low  $C_{iss}$ :  $C_{iss} = 2100 \text{ pF TYP.}$  ( $V_{DS} = 25 \text{ V}$ ,  $V_{GS} = 0 \text{ V}$ )
- Logic level drive type
- Designed for automotive application and AEC-Q101 qualified

**Ordering Information**

Part No.	Lead Plating	Packing		Package
NP40N10YDF-E1-AY *1	Pure Sn (Tin)	Tape 2500 p/reel	Taping (E1 type)	8-pin HSON
NP40N10YDF-E2-AY *1			Taping (E2 type)	
NP40N10VDF-E1-AY *1	Pure Sn (Tin)	Tape 2500 p/reel	Taping (E1 type)	TO-252 (MP-3ZP)
NP40N10VDF-E2-AY *1			Taping (E2 type)	
NP40N10PDF-E1-AY *1	Pure Sn (Tin)	Tape 800 p/reel	Taping (E1 type)	TO-263 (MP-25ZP)
NP40N10PDF-E2-AY *1			Taping (E2 type)	

Note: \*1. Pb-free (This product does not contain Pb in the external electrode.)

**Absolute Maximum Ratings (T<sub>A</sub> = 25°C)**

Item	Symbol	Ratings	Unit
Drain to Source Voltage (V <sub>GS</sub> = 0 V)	V <sub>DSS</sub>	100	V
Gate to Source Voltage (V <sub>DS</sub> = 0 V)	V <sub>GSS</sub>	±20	V
Drain Current (DC) (T <sub>C</sub> = 25°C)	I <sub>D(DC)</sub>	±40	A
Drain Current (pulse) *1	I <sub>D(pulse)</sub>	±80	A
Total Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>T1</sub>	120	W
<b>NP40N10YDF</b> Total Power Dissipation (T <sub>A</sub> = 25°C) *2	P <sub>T2</sub>	1.0	W
<b>NP40N10VDF</b> Total Power Dissipation (T <sub>A</sub> = 25°C) *2		1.2	
<b>NP40N10PDF</b> Total Power Dissipation (T <sub>A</sub> = 25°C)		1.8	
Channel Temperature	T <sub>ch</sub>	175	°C
Storage Temperature	T <sub>stg</sub>	-55 to +175	°C
Single Avalanche Current *3	I <sub>AS</sub>	25	A
Single Avalanche Energy *3	E <sub>AS</sub>	61	mJ

**Thermal Resistance**

Channel to Case Thermal Resistance	R <sub>th(ch-C)</sub>		1.25	°C/W
Channel to Ambient Thermal Resistance *2	R <sub>th(ch-A)</sub>	NP40N10YDF	150	°C/W
		NP40N10VDF	125	°C/W
		NP40N10PDF	83.3	°C/W

Notes: \*1. T<sub>C</sub> = 25°C, PW ≤ 10 μs, Duty Cycle ≤ 1%

\*2. Mounted on glass epoxy substrate of 40 mm x 40 mm x 1.6 mm with 4% copper area (35 μm)

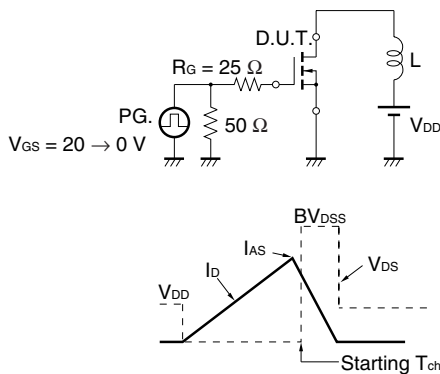
\*3. T<sub>ch(start)</sub> = 25°C, V<sub>DD</sub> = 50 V, R<sub>G</sub> = 25 Ω, L = 100 μH, V<sub>GS</sub> = 20 V → 0 V

**Electrical Characteristics (T<sub>A</sub> = 25°C)**

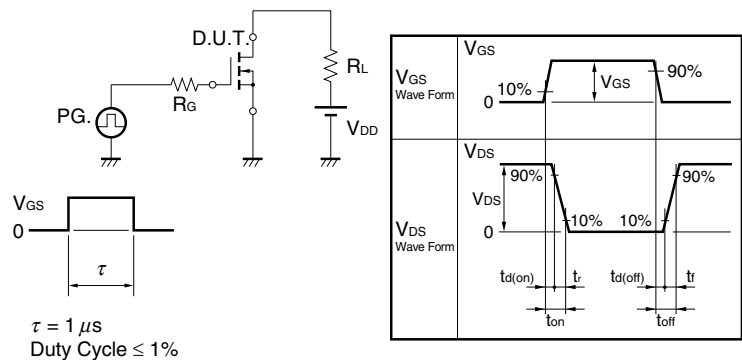
Item	Symbol	Min	Typ	Max	Unit	Test Conditions	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			1	μA	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V	
Gate Leakage Current	I <sub>GSS</sub>			±100	nA	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V	
Gate to Source Threshold Voltage	V <sub>GS(th)</sub>	1.5	2.0	2.5	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	
Forward Transfer Admittance *1	y <sub>fs</sub>	20	40		S	V <sub>DS</sub> = 5.0 V, I <sub>D</sub> = 20 A	
Drain to Source On-state Resistance *1	NP40N10YDF	R <sub>DS(on)1</sub>		21	25	mΩ	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A
		R <sub>DS(on)2</sub>		23	30	mΩ	V <sub>GS</sub> = 5.0 V, I <sub>D</sub> = 20 A
		R <sub>DS(on)3</sub>		24	36	mΩ	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 20 A
	NP40N10VDF	R <sub>DS(on)1</sub>		21	26	mΩ	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A
		R <sub>DS(on)2</sub>		23	31	mΩ	V <sub>GS</sub> = 5.0 V, I <sub>D</sub> = 20 A
		R <sub>DS(on)3</sub>		24	37	mΩ	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 20 A
	NP40N10PDF	R <sub>DS(on)1</sub>		21	27	mΩ	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A
		R <sub>DS(on)2</sub>		23	32	mΩ	V <sub>GS</sub> = 5.0 V, I <sub>D</sub> = 20 A
		R <sub>DS(on)3</sub>		24	38	mΩ	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 20 A
Input Capacitance	C <sub>iss</sub>		2100	3150	pF	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,	
Output Capacitance	C <sub>oss</sub>		200	300	pF	f = 1 MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>		80	144	pF		
Turn-on Delay Time	t <sub>d(on)</sub>		15	33	ns	V <sub>DD</sub> = 50 V, I <sub>D</sub> = 20 A,	
Rise Time	t <sub>r</sub>		16	40	ns	V <sub>GS</sub> = 10 V,	
Turn-off Delay Time	t <sub>d(off)</sub>		60	120	ns	R <sub>G</sub> = 0 Ω	
Fall Time	t <sub>f</sub>		5	13	ns		
Total Gate Charge	Q <sub>G</sub>		47	71	nC	V <sub>DD</sub> = 80 V,	
Gate to Source Charge	Q <sub>GS</sub>		8		nC	V <sub>GS</sub> = 10 V,	
Gate to Drain Charge	Q <sub>GD</sub>		12		nC	I <sub>D</sub> = 40 A	
Body Diode Forward Voltage *1	V <sub>F(S-D)</sub>		0.9	1.5	V	I <sub>F</sub> = 40 A, V <sub>GS</sub> = 0 V	
Reverse Recovery Time	t <sub>rr</sub>		67		ns	I <sub>F</sub> = 40 A, V <sub>GS</sub> = 0 V,	
Reverse Recovery Charge	Q <sub>rr</sub>		162		nC	di/dt = 100 A/μs	

Note: \*1. Pulsed test

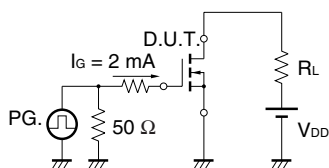
**TEST CIRCUIT 1 AVALANCHE CAPABILITY**



**TEST CIRCUIT 2 SWITCHING TIME**

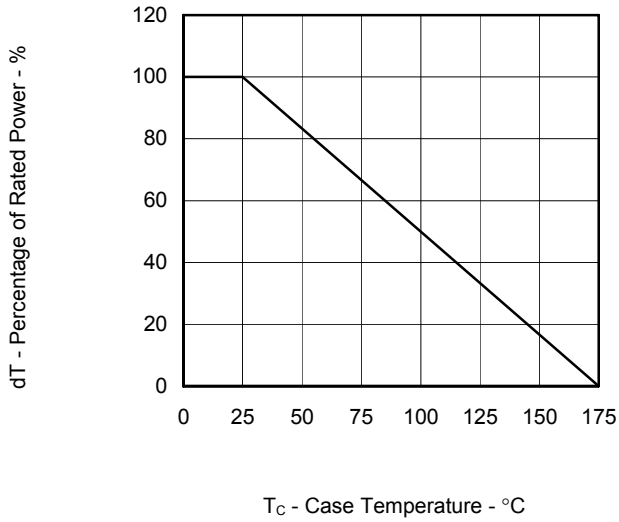


**TEST CIRCUIT 3 GATE CHARGE**

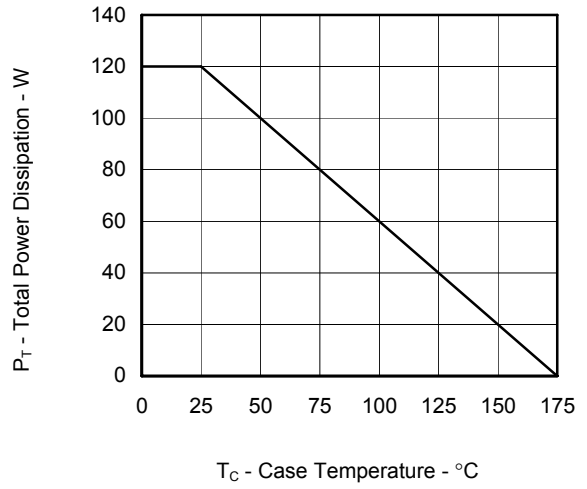


Typical Characteristics (T<sub>A</sub> = 25°C)

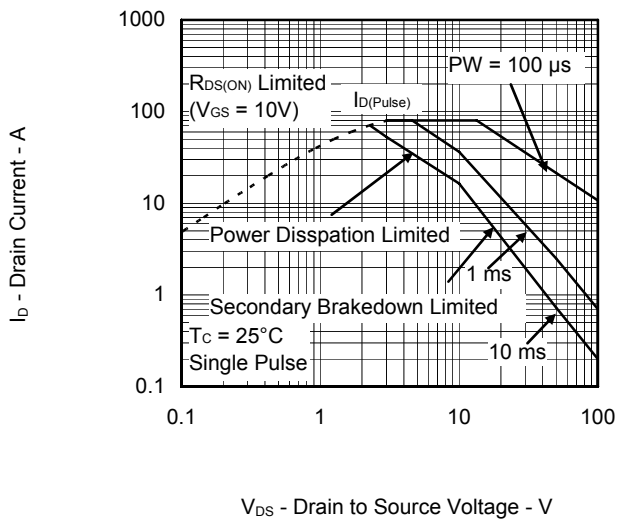
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



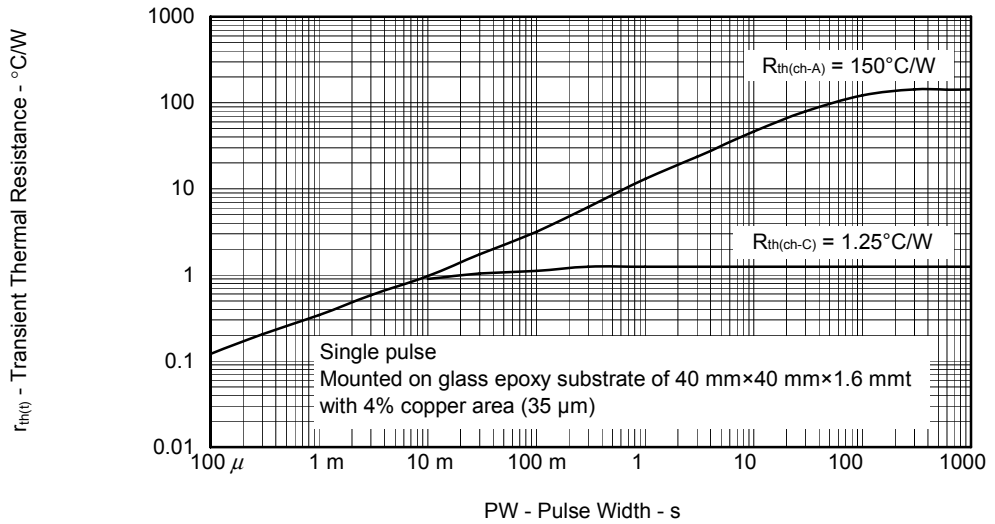
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



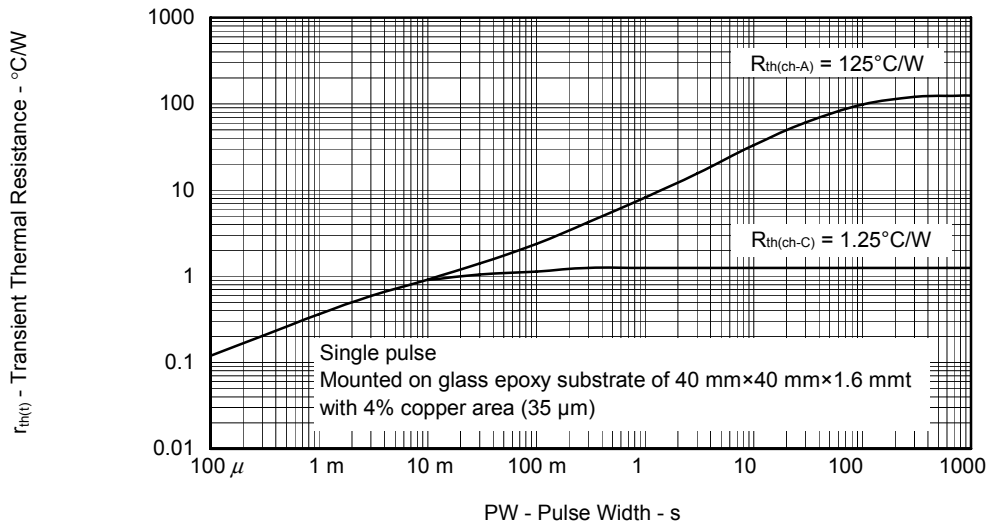
FORWARD BIAS SAFE OPERATING AREA



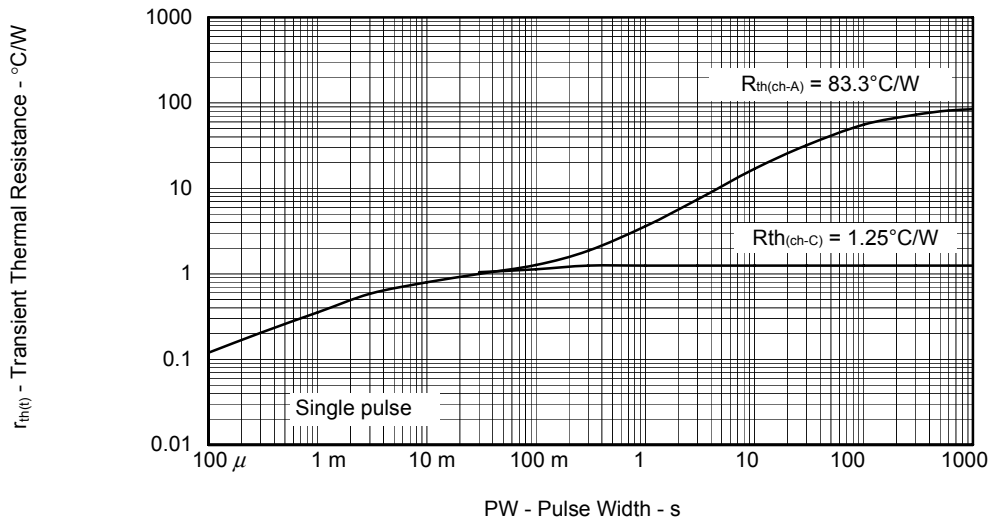
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH (NP40N10YDF)



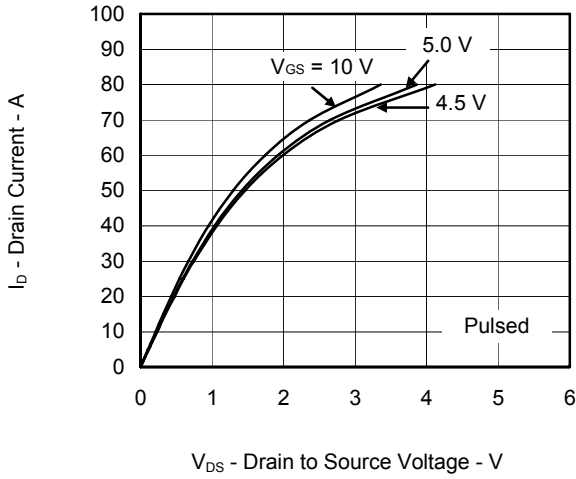
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH (NP40N10VDF)



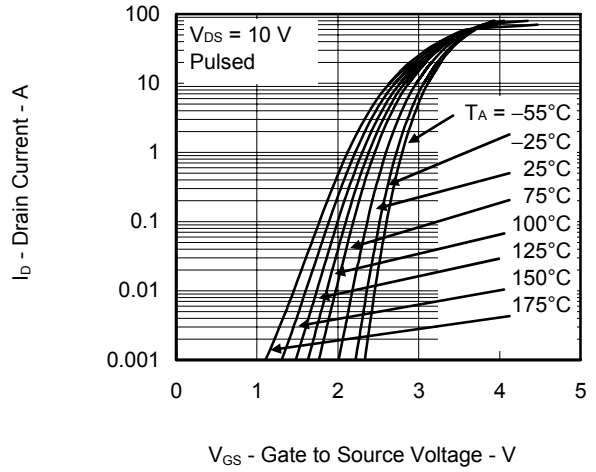
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH (NP40N10PDF)



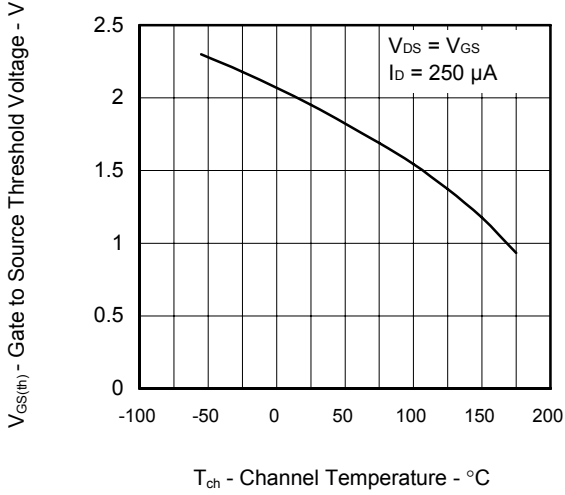
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



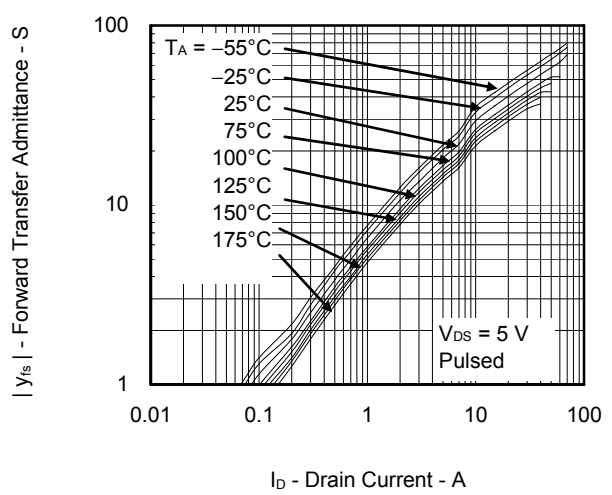
FORWARD TRANSFER CHARACTERISTICS



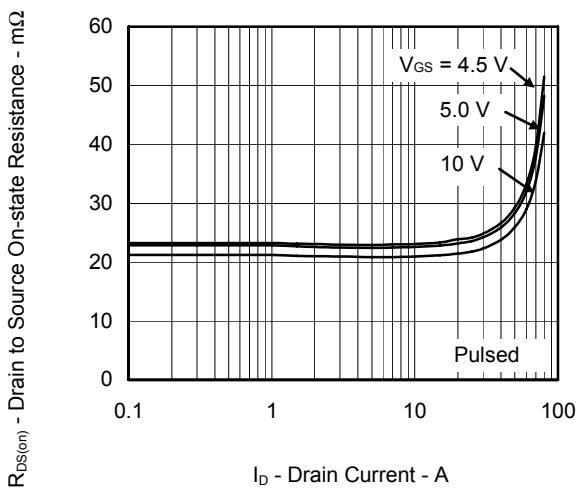
GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE



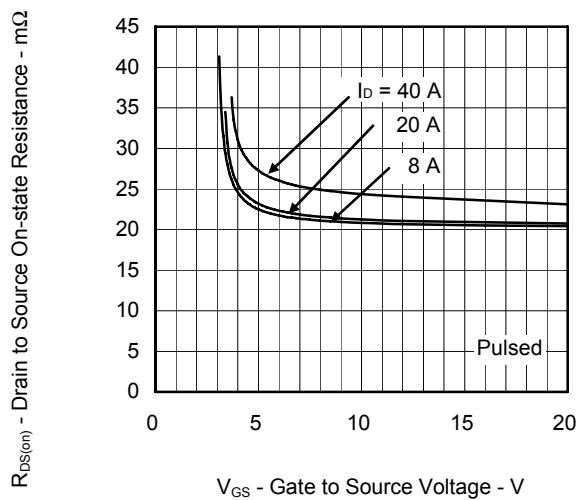
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



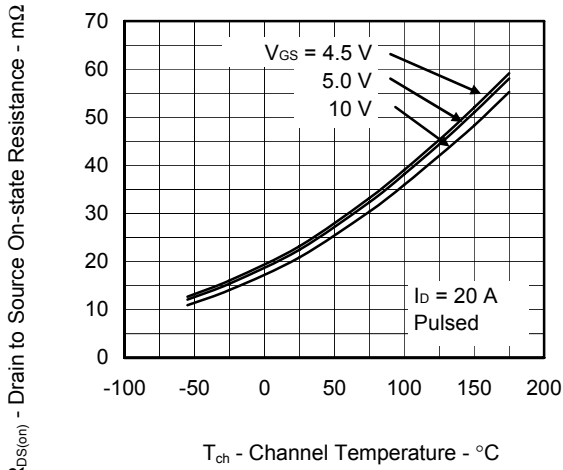
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



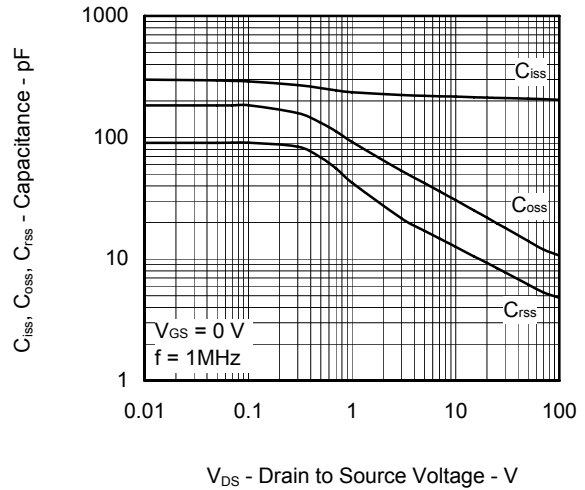
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



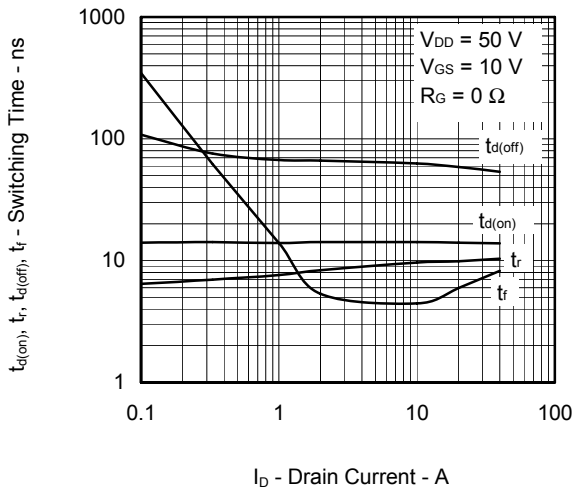
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



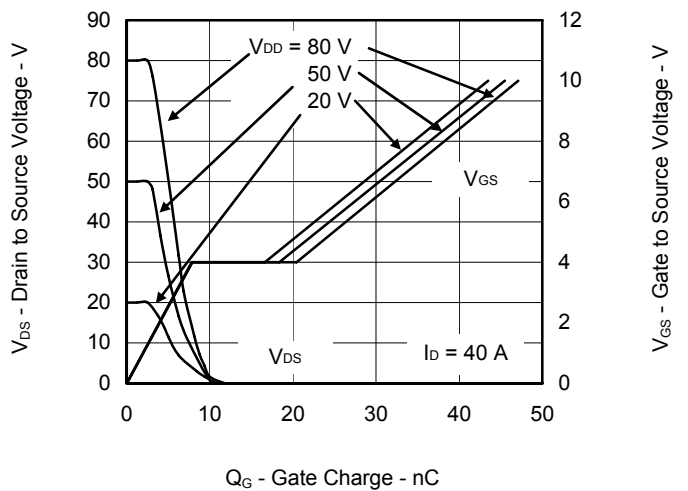
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



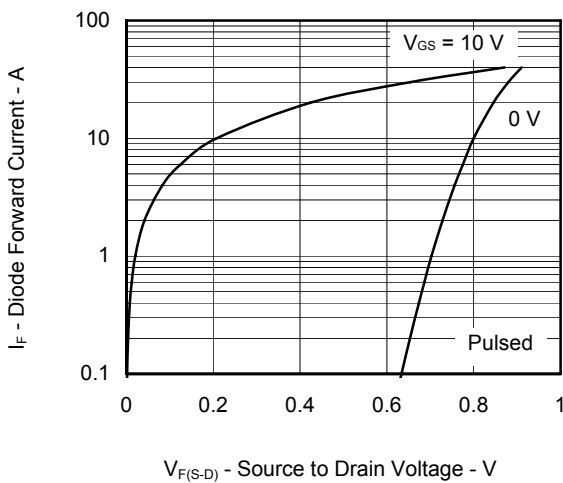
SWITCHING CHARACTERISTICS



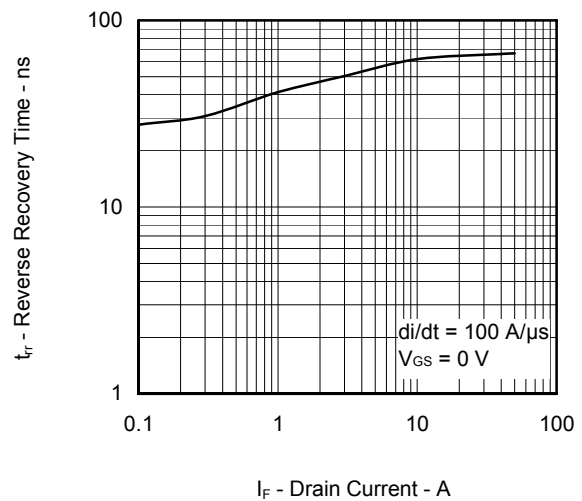
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE

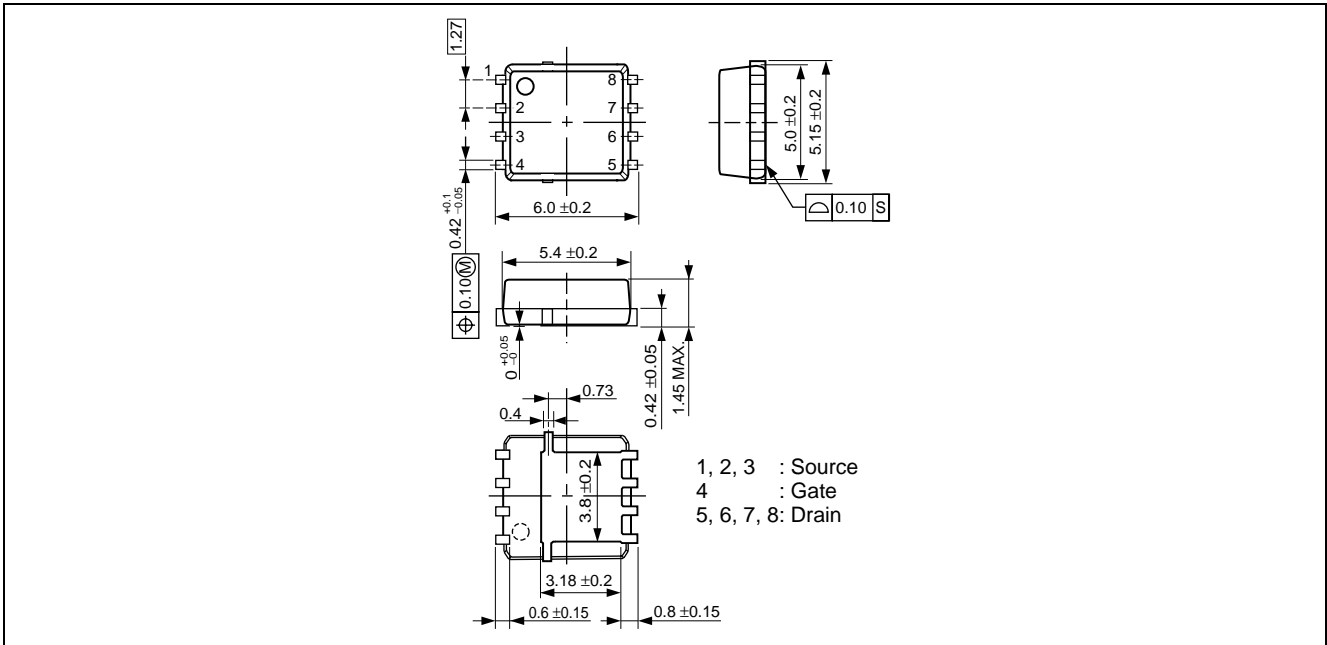


REVERSE RECOVERY TIME vs. DRAIN CURRENT

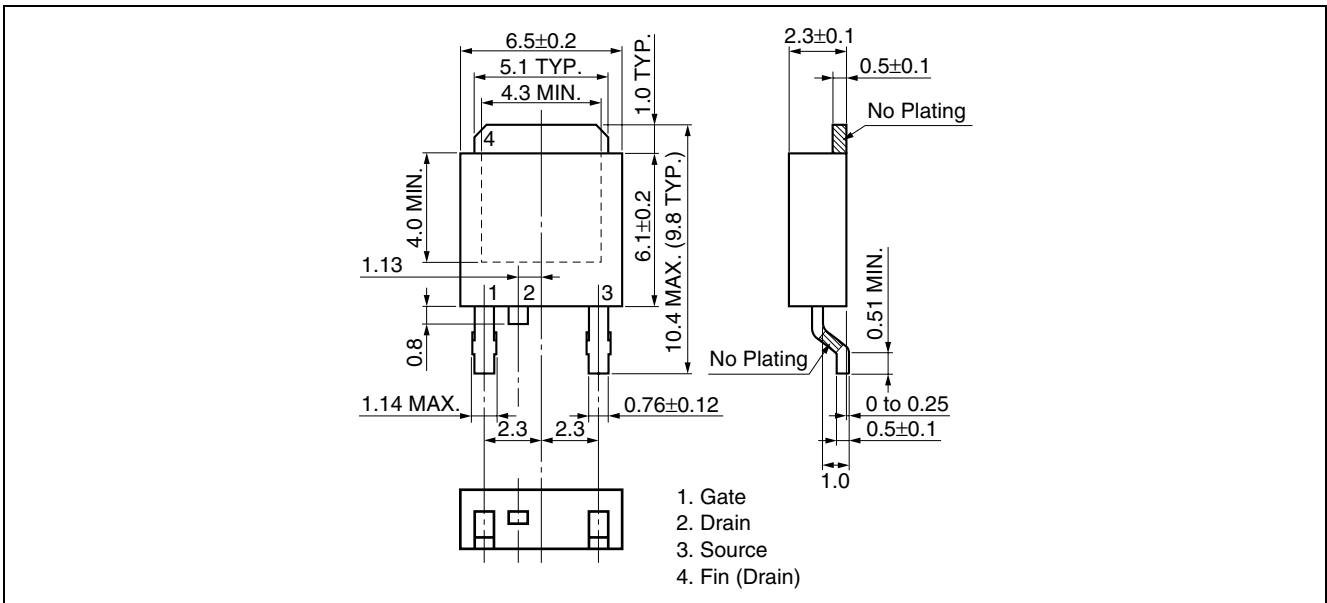


Package Drawings (Unit: mm)

8-pin HSON (Mass: 0.13 g TYP.)

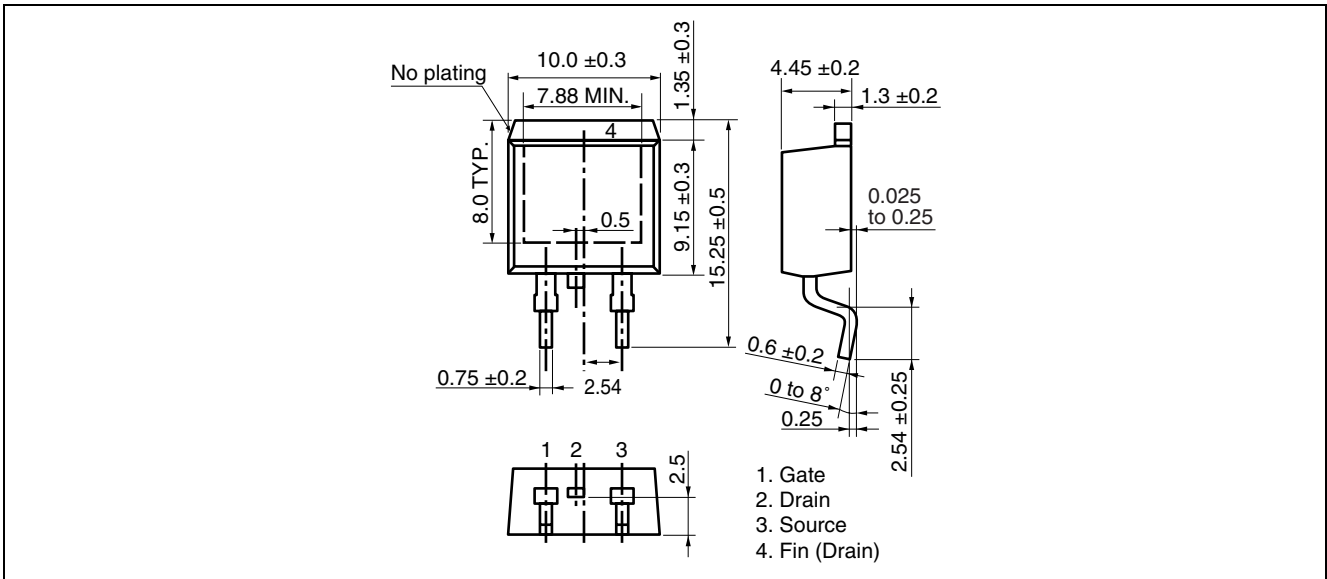


TO-252 (MP-3ZP) (Mass: 0.27 g TYP.)

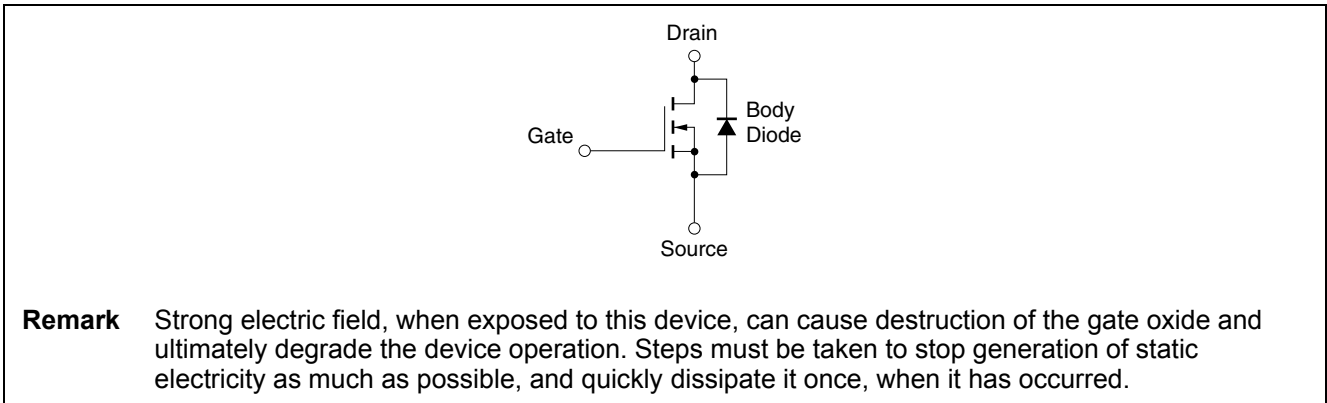




TO-263 (MP-25ZP) (Mass: 1.48 g TYP.)



## Equivalent Circuit



<b>Revision History</b>	<b>NP40N10YDF, NP40N10VDF, NP40N10PDF Data Sheet</b>
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<b>Rev.</b>	<b>Date</b>	<b>Description</b>	
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1.00	Jun 07, 2011	–	First Edition Issued

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